

## ORGANIZING INFORMATION

### THE CONFERENCE IS HELD AT:

Střední škola informatiky  
Čichnova 23, 624 00 BRNO-Komín

### How to get there: see incl. plan by a car

From the Brno Trade Fair Exhibition Centre go in direction Brno-dam. After approx. 4 km you will see the OPEL car shop centre, on the left side. At the crossroads in front of the OPEL go to the left, at the next crossroads to the right and on the right side you will see an educational centre:

Střední škola informatiky  
street Čichnova 23, BRNO-Komín

### BINDING APPLICATIONS:

Will be mailed together with obligatory demand for accommodation and meals before **October 13, 2016** to the address:

SMT-INFO consortium  
Údolní 53, 602 00 Brno  
CZECH REPUBLIC  
e-mail: [smtinfo@nextra.cz](mailto:smtinfo@nextra.cz)

### Accommodation:

Participants will be accommodated in the BOBY CENTRUM Brno \*\*\*

### Registration:

In the conference hall  
October 18, 2016 11.30 – 12.20 p.m.  
October 19, 2016 8.30 – 9.00 a.m.

### PROFESSIONAL GUARANTOR:

SMT-INFO, Údolní 53, 602 00 Brno  
CZECH REPUBLIC

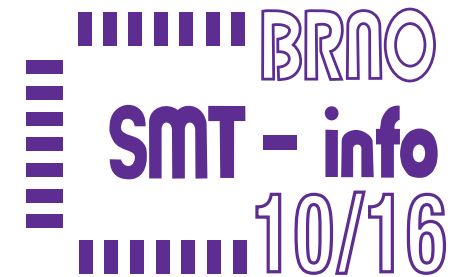
tel.: 00420-541 146 113  
mobil: 00420-602 542 966  
e-mail: [smtinfo@nextra.cz](mailto:smtinfo@nextra.cz)  
Internet: [www.smtinfo.cz](http://www.smtinfo.cz)

## SMT-INFO CONSORTIUM

in cooperation with

**FEKT VUT Brno**  
and  
**SŠ INFORMATIKY BRNO**

have the pleasure to invite you to  
25<sup>th</sup> international conference



## SOLDERING AND CLEANING PCB's IN ELECTRONICS

### NEW TRENDS IN MICROELECTRONICS

### SOLDER JOINT DEFECTS

BRNO, October 18–19, 2016  
SŠ informatiky  
Čichnova 23, Brno-Komín

event code 10/16

### SMTinfo CONSORTIUM Invitation



Media Partner of the Conference is the Magazine  
PCB ELECTRONICS A-Z



## CONFERENCE ORIENTATION:

- SOLDERING AND CLEANING IN ELECTRONICS
- NEW TRENDS IN MICROELECTRONICS
- TECHNIQUES IN REPAIRING
- SOLDER JOINT DEFECTS

## PROFESSIONAL OFFER

- Conference participants will be acquainted with the latest information on above mentioned topics presented by specialist from prestigious companies.
- In a room adjacent the lecture theatre, the following company stands will be installed and professional literature and demonstration equipment will be offered there:

**ABETEC – ATF, ECD, FINETECH, MARTIN – SMT ADOPT**

**AIM SOLDER EUROPE**

**AMTECH**

**AMTEST**

**ERMEG**

**PAN ELECTRONICS**

- Advertisement tables will be available for the conference participants and visitors, providing propagation of their own products and offer of non-used/used technological equipment and services.

## THEMATIC ORIENTATION OF OTHER EVENTS

### ORGANIZED BY SMT-INFO:

**SMT-INFO 02/17**                      **Brno, 7th February, 2017**  
Technical and Business Seminar

- PCB DESIGN SYSTEMS
- PCB PRODUCTION AND DEFECTS
- COMPLEX PRODUCTION LINES FOR MODERN ASSEMBLY
- INSPECTION SYSTEMS

## PROFESSIONAL GUARANTOR:

**SMT-INFO CONSORTIUM, Údolní 53, 602 00 Brno**

**mobil: 00420-602 542 966**

**e-mail: smtinfo@nextra.cz**

## CONFERENCE SCHEDULE

### Tuesday, October 18, 2016

- 12.20 - Opening, Introduction
- 12.30 - Miniaturisation in Electronics and How to Produce Products with Higher Integration /R. Boyle, HENKEL, D. Sameš, OEM AUTOMATIC Zdiby/
- 13.10 - INTERSELECT – Latest and Trend in Selective Soldering /P. Grosse, INTERSELECT, L. Pokorný, AMTEST CZECH REPUBLIC Brno/
- 13.40 - Temperature Profile – Failures in Reflow Soldering Process /K. Dušek, ČVUT Praha/
- 14.00 - Break, Refreshment, Coffee
- 14.20 - Wire bonding – New Trends, Laser Bonding /J. Sedlmair, F&K DELVOTEC BONDTECHNIK, J. Vondráček, AMTEST CZECH REPUBLIC Brno/
- 15.00 - Reducing Floor Space Requirements for Thermal Processes > 20 min. (Curing, Drying etc.) /D. Hayn, CERACON Weikersheim/
- 15.20 - Discussion
- 15.30 - Technical Cleanliness – New Trends in PCBA Cleaning /M. Šaffer, PBT Rožnov pod Radhoštěm/
- 15.50 - Cleaning Process Performance and its Validation /V. Sítko, PBT WORKS Rožnov pod Radhoštěm/
- 16.10 - Temperature Profiles Verification in Soldering Machines /W. Antoniák, ECD, M. Abel, ABETEC Ostřešany/
- 16.30 - PCB's Repairs with BGA and SMD from 008004 /A. Schmidt, FINETECH, M. Abel, ABETEC Ostřešany/
- 16.50 - Electromigration in PCB Assemblies /J. Starý, FEKT VUT Brno/
- 17.10 - Discussion, Closing the First Day of Conference
- 17.30 – 21.00 p.m.**

**Friendly Meeting of Conference Participants and Lecturers with Dinner and Refreshment.**

### Wednesday, October 19, 2016

- 9.00 - Opening the Second Day of Conference
- 9.10 - Effect of Bi Content on Properties of Low Silver SAC Alloys /A. Sedlák, AIM SOLDER EUROPE/
- 9.30 - APOLLO – SEIKO Robotic Soldering /T. Ševčík, AMTECH Brno/
- 10.00 - Refreshment, Coffee
- 10.20 - Vacuum and Fluxless Soldering /P. Martin, HELLER INDUSTRIES, A. Kollár, AMTEST CZECH REPUBLIC Brno/
- 11.00 - Economic Solution – Table Selective Soldering Waves and Small Soldering Waves /M. Berberich, ATF, M. Abel, ABETEC Ostřešany/
- 11.20 - BGA Repair Stations with Volumetric Dispensers /F. Leitenstern, MARTIN –SMT, M. Abel, ABETEC Ostřešany/
- 11.40 - Discussion
- 11.50 - CERA – Reconstruction and Visualisation Software for X-Ray Failure Analysis using Tomosynthesis and CT /P. Koch, DAGE, P. Lacko, QUIPTECH Brno/
- 12.30 - Possibilities for Coating Electronics for Design of Electronic Assemblies /R. Příkryl, ACC SILICONES Brno/
- 13.00 - Protection of Electronic Parts and Assemblies – ESD Control Program (IEC 61340-5-1:2016, 4-6:2015, 4-9:2016, EOS/ESD Association Fundamentals 2014) /K. Jurák, Z. Nejezchlebová, ÚNMZ Praha/
- 13.20 - Discussion, Closing the Second Day of Conference
- 13.50 - Lunch

**Lectures in English and German will be interpreted.  
Program changes reserved.**

*Obligatory application for international conference*

**SOLDERING AND CLEANING PCB's  
IN ELECTRONICS**

**NEW TRENDS IN MICROELECTRONICS**

**SOLDER JOINT DEFECTS**

**October 18–19, 2016**

Name and surname, title .....

Factory name and address (ZIP code) .....

.....

Job function .....

Telephone ..... Telefax .....

e-mail .....

**Evening Party**

October 18, 2016 **yes-no**

**Lunch**

October 19, 2016 **yes-no**

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Participant signature

.....  
Stamp and signature  
of the organization

SMT-INFO consortium  
Údolní 53  
602 00 BRNO  
Czech Republic